

CLAIMS:

1. A method comprising:
grounding a molding tool so as to reduce charge dissipation through an air
5 interface between a stamper and a mirror block of the molding tool.
2. The method of claim 1, further comprising creating a molded component using
the molding tool.
- 10 3. The method of claim 1, further comprising grounding a moving side of the
molding tool.
4. The method of claim 1, further comprising grounding the stamper.
- 15 5. The method of claim 1, wherein grounding the molding tool includes creating an
electrically conductive path between the molding tool and a ground potential.
6. The method of claim 5, wherein the electrically conductive path includes a ground
strap coupled from a moving side of the molding tool to the ground potential.
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7. A molding tool comprising:
a moving side;
a non-moving side; and
a substantially non-resistive path to ground coupled to the moving side.
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8. The molding tool of claim 7, wherein the substantially non-resistive path to
ground comprises a ground strap.
9. The molding tool of claim 7, further comprising substantially non-resistive paths
30 coupled to both the moving side and non-moving sides.

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10. The molding tool of claim 7, wherein the non-moving side includes a mirror block and a stamper separated by a small air gap.
11. The molding tool of claim 10, wherein the stamper is a nickel stamper and the
5 mirror block includes a diamond-like carbon coating.
12. The molding tool of claim 10, wherein the stamper is a nickel stamper and the mirror block includes a titanium nitride coating.
- 10 13. The molding tool of claim 10, wherein the stamper is vacuum drawn to the mirror block.
14. The molding tool of claim 7, wherein the non-moving side includes a mirror block and does not include a stamper.
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15. The molding tool of claim 7, wherein both the moving side and non-moving side include a mirror block and a stamper.
16. The molding tool of claim 7, wherein the molding tool is an injection molding
20 tool.
17. A molding tool comprising:
a first side and a second side collectively defining a mold cavity; and
a ground strap defining at least a portion of a substantially non-resistive path from
25 the mold cavity to ground.
18. The molding tool of claim 17, wherein the molding tool includes a stamper and a mirror block on the first side, wherein the stamper and mirror block are separated by a small air gap, and wherein the ground strap substantially reduces charge dissipation
30 across the small air gap.

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19. The molding tool of claim 18, wherein the ground strap is coupled to the second side.
20. The molding tool of claim 19, wherein the second side is a moving side and the first side is a non-moving side.
21. The molding tool of claim 17, wherein the molding tool is an injection molding tool.
- 10 22. A molding system comprising:
a molding tool including a moving side, a non-moving side, and a substantially non-resistive path to ground coupled to the moving side;
a control unit coupled to the molding tool to control a molding process of the molding tool; and
15 a robotic arm coupled to the control unit for receiving molded components from the molding tool.